The special issue aims at discussing recent advances in modelling emerging electromagnetic materials, structures, and devices at microwave, terahertz, and optical frequencies by computational electromagnetics and multiphysics algorithm.

The special issue of papers will consider the latest research in but not limited to:

- Modeling of emerging electromagnetic materials including 2D materials (graphene, transition metal dichalcogenides, etc), flexible organic materials, liquid crystals, and perovskite materials
- Modeling of emerging electromagnetic structures and devices including (spoof) surface plasmon, topological insulator, and metamaterial/metasurface
- Modeling of configurable, tunable, and active electromagnetic structures and devices
- Modeling of nonlinear electromagnetic effects in nonlinear circuits, magnetic devices, microwave plasma, and nonlinear optical materials
- Modeling of quantum effects in electromagnetic materials, structures and devices
- Modeling of multiphysics effects in electromagnetic materials, structures and devices including electromagnetic-electrical-thermal-mechanical effects, optical-electrical-thermal effects, optical-acoustic effects, etc
- Multiscale and multiphase issues in modeling emerging electromagnetic materials, structures, and devices
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